# Monthly LabAdviser update: 11/4 2014

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| Updated Subject | Contributor | Link to the updated pages |
| **Help getting started**  Links to You Tube films about what a wiki is and how to edit it are add to Process2Share | **Berit G. Herstrøm @danchip** | <http://process2share.danchip.dtu.dk/index.php/Main_Page> |
| **Piranha:**  Correction: H2O2, is a very strong oxidant. | **Kresten Yvind @Fotonik**  **Karen Birkelund @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Wafer_cleaning/7-up_%26_Piranha> |
| **Developers**  Comparison table for the developers and info on each developer has been added | **Thomas Anhøj**  **@Danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Development> |
| **Exposure doses for UV resist**  Added to resist overview table  Added to Aligner info sections | **Thomas Anhøj**  **@Danchip** | [UVLithography](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/UVLithography)  [UVExposure%23KS\_Aligner](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/UVExposure%23KS_Aligner)  [UVExposure%23Aligner-6inch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/UVExposure%23Aligner-6inch) |
| **Furnace LPCVD TEOS**  New result for the standard recipe “TEOS” | **Christian Østergaard @Nanotech** | [/Deposition\_of\_TEOS\_using\_LPCVD#Expected\_results\_when\_using\_the\_standard\_recipes\_on\_the\_LPCVD\_TEOS\_furnace](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_TEOS/Deposition_of_TEOS_using_LPCVD#Expected_results_when_using_the_standard_recipes_on_the_LPCVD_TEOS_furnace) |
| **Deposition of Si**  Updating page on deposition of Si | **Katharina Nilson**  **@Danchip** | [Deposition\_of\_Silicon](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon)  [Si\_sputter\_in\_Wordentec](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Si_sputter_in_Wordentec)  [Si\_sputter\_Alcatel](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon/Si_sputter_Alcatel) |
| **Deposition of AlTi/AlTi deposition in PVD co-sputter co-evaporation**  New page – information transferred from other page | **Katharina Nilson**  **@Danchip** | [AlTi\_deposition\_in\_PVD\_co-sputter\_co-evaporation](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_AlTi/AlTi_deposition_in_PVD_co-sputter_co-evaporation) |
| **ALD**  Equipment page is ready.  Process info on Al2O3. | **Pernille V. Larsen @danchip**  **Evgeniy Shkondin @danchip** | [ALD\_Picosun\_R200](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/ALD_Picosun_R200)  [Al2O3\_deposition\_using\_ALD](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_Film_deposition/ALD/Al2O3_deposition_using_ALD) |
| **Updated comparison pages:**  Wafer Bonding  Element Analysis  Deposition of TiO2  Annealing  Wet HF etch of Bulk Glass  Deposition of: Al, Ge, TiW, Ti, Cr, Ni, Cu, Mo, Pd, Ag, Ta, Pt, Au, NiV, NiCr, AlTi | **Elena**  **Jonas**  **Berit**  **Mikkel**  **Katharina**  **@Danchip** |  |